

METHOD OF JOINING LAMINATES FOR Z-AXIS INTERCONNECTION

Abstract of the Disclosure

A method of forming a laminated composite printed wiring structure of a plurality of at least three superimposed subcomposites having organic substrates is provided. Via openings in the subcomposite structures having conductive paste therein are positioned to align with openings in at least one adjacent subcomposite structure also filled with conductive paste that is to be joined thereto. Printed wiring is provided on at least one face of one subcomposite structure. A fixture with pins which extends through index openings in the composites are provided to mount masks for screening paste and stacking of the composites is provided. After screening of paste, and partially curing of the paste, in each composite, a group of composites is placed on the fixture and the pastes are fully cured to form a unitary structure.